

WHAT IS CLAIMED IS:

1. A method for cutting integrated circuit packages, comprising:  
providing an integrated circuit package; and  
cutting the integrated circuit package with a water jet.
2. The method of Claim 1, wherein cutting the integrated circuit package with a water jet comprises:  
positioning the integrated circuit package adjacent a water jet;  
pressurizing the water jet such that the water jet is operable to cut the integrated circuit package; and  
cutting the integrated circuit package to a predetermined shape.
3. The method of Claim 1, wherein providing an integrated circuit package comprises providing a ball grid array package.
4. The method of Claim 1, wherein cutting the integrated circuit package with a water jet comprises cutting the integrated circuit package with a water jet having a plurality of abrasive particles.
5. The method of Claim 2, wherein pressurizing the water jet comprises pressurizing the water jet to a pressure between approximately 500 psi and approximately 2500 psi.
6. The method of Claim 1, wherein cutting the integrated circuit package with a water jet comprises cutting a plurality of integrated circuit packages by directing the water jet along at least one of a plurality of edges of the integrated circuit packages.
7. The method of Claim 1, wherein cutting the integrated circuit package with a water jet comprises cutting the integrated circuit package such that an interior portion of the integrated circuit package is accessible for testing.

8. A method for cutting integrated circuit packages, comprising:  
providing an integrated circuit package;  
positioning the integrated circuit package adjacent a water jet;  
pressurizing the water jet such that the water jet is operable to cut the  
integrated circuit package; and  
cutting the integrated circuit package to a desired shape.

9. The method of Claim 8, wherein providing an integrated circuit  
package comprises providing a ball grid array package.

10. The method of Claim 8, wherein cutting the integrated circuit package  
to a desired shape comprises cutting the integrated circuit package with a water jet  
having a plurality of abrasive particles.

11. The method of Claim 8, wherein pressurizing the water jet comprises  
pressurizing the water jet to a pressure between approximately 500 psi and  
approximately 2500 psi.

12. The method of Claim 8, wherein cutting the integrated circuit package  
to a desired shape comprises cutting a plurality of integrated circuit packages by  
directing the water jet along at least one of a plurality of edges of the integrated circuit  
packages.

13. The method of Claim 8, wherein cutting the integrated circuit package  
to a desired shape comprises cutting the integrated circuit package such that an  
interior portion of the integrated circuit package is accessible for testing.

14. A system for cutting an integrated circuit package, comprising:  
a computer operable to generate a predetermined cut pattern for the  
integrated circuit; and  
a water jet machining system operatively coupled to the computer and  
operable to generate a water jet with a suitable pressure for cutting the  
integrated circuit package into the predetermined cut pattern.

15. The system of Claim 14, wherein the water jet machining system  
comprises:

a water supply;  
an intensifier pump operatively coupled to the water supply and  
operable to pump water through a conduit;  
a hydraulic unit operatively coupled to the intensifier pump;  
an attenuator operatively coupled to the water and operable to dampen  
pressure fluctuations of the water in the conduit;  
a valve coupled to the conduit and operable to control the flow of the  
water; and  
a nozzle coupled to conduit operable to direct the water along the  
predetermined cut pattern.

16. The system of Claim 14, wherein the integrated circuit package is a  
ball grid array package.

17. The system of Claim 14, wherein the water jet comprises a plurality of  
abrasive particles.

18. The system of Claim 14, wherein the suitable pressure is between  
approximately 500 psi and approximately 2500 psi.

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20. The system of Claim 14, wherein the predetermined cut pattern comprises a pattern through an interior portion of the integrated circuit package such that the interior portion is accessible for testing.